VNI2140

Dual high side smart power solid state relay

Datasheet - production data

PowerSSO-12™

Features

- Nominal current: 0.5 A per channel
- Shorted-load protections
- Junction overtemperature protection
- Case overtemperature protection for thermal independence of the channels
- Thermal case shutdown restart not simultaneous for the various channels
- Protection against loss of ground
- Current limitation 1 A per channel
- Undervoltage shutdown
- Open-load in off-state and short to V_{CC} detection
- Open-drain diagnostic outputs
- 3.3 V CMOS/TTL compatible inputs
- Fast demagnetization of inductive loads
- Conforms to IEC 61131-2

Description

The VNI2140J is a monolithic device designed using STMicroelectronics' VIPower technology. The device drives two independent resistive or inductive loads with one side connected to ground. Active current limitation prevents a drop in system power supply in cases of shorted-load, and built-in thermal shutdown protects the chip from damage due to overtemperature and short-circuit. In overload conditions, channel turns OFF and ON automatically to maintain the junction temperature between TTSD and TR. If the case temperature reaches TCSD, the overloaded channel is turned OFF and restarts only when case temperature decreases down to TCR. In order to avoid high-peak current from the supply, when more than one channel is overloaded the TCSD restart is not simultaneous. Non overloaded channels continue to operate normally. The open-drain diagnostics output indicates overtemperature conditions and open-load in off state.

Table 1. Device summary

Order codes	Package	Packaging
VNI2140J	PowerSSO-12™	Tube
VNI2140JTR		Tape and reel

Table 2. Main features

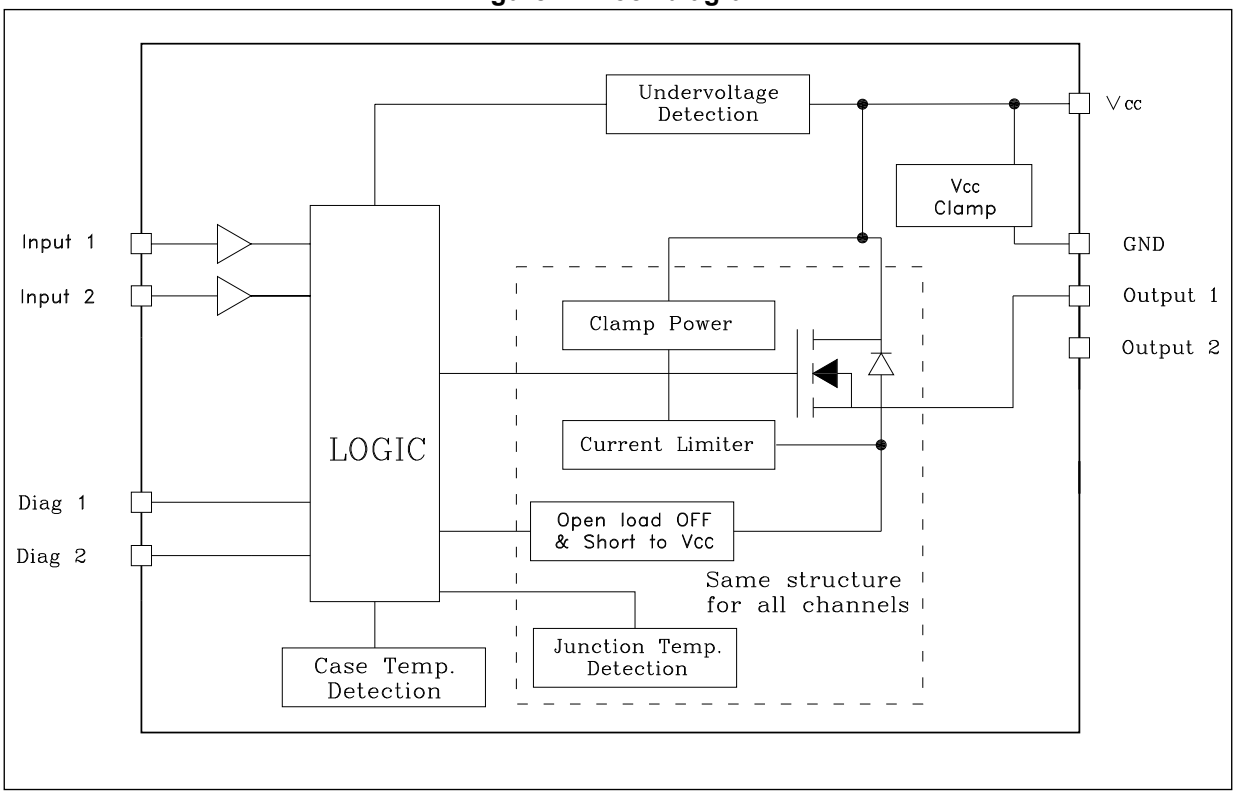
Type	V_{demag} (1)	R_{DSon} (1)	I_{out} (1)	V_{CC}
VNI2140J	V_{CC} -45 V	0.08 Ω	1 A (2)	45 V

1. Per channel.
2. Current limitation.

Contents

1 Block diagram

Figure 1. Block diagram



2 Pin connections

Figure 2. Pin connections (top view)

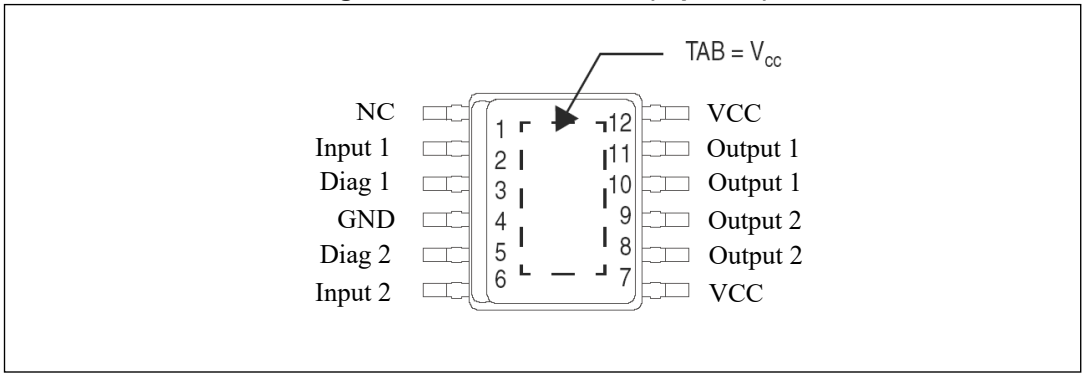


Table 3. Pin description

No.	Name	Description
1	NC	Not connected
2	Input 1	Channel 1 input 3.3 V CMOS/TTL compatible
3	Diag 1	Channel 1 diagnostic in open-drain configuration
4	GND	Device ground connection
5	Diag 2	Channel 2 diagnostic in open-drain configuration
6	Input 2	Channel 2 input 3.3 V CMOS/TTL compatible
7	VCC	Supply voltage
8	Output 2	Channel 2 power stage output, internally protected
9	Output 2	Channel 2 power stage output, internally protected
10	Output 1	Channel 1 power stage output, internally protected
11	Output 1	Channel 1 power stage output, internally protected
12	VCC	Supply voltage
TAB	TAB	Supply voltage

3 Maximum ratings

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Power supply voltage	45	V
$-V_{CC}$	Reverse supply voltage	-0.3	V
I_{GND}	DC ground reverse current	-250	mA
I_{OUT}	Output current (continuous)	Internally limited	A
I_R	Reverse output current (per channel)	-5	A
I_{IN}	Input current (per channel)	± 10	mA
V_{IN}	Input voltage	$+V_{CC}$	V
V_{DIAG}	Diag pin voltage	$+V_{CC}$	V
I_{DIAG}	Diag pin current	± 10	mA
V_{ESD}	Electrostatic discharge (R = 1.5 kΩ; C = 100 pF)	2000	V
E_{AS}	Single pulse avalanche energy per channel, all channels driven simultaneously at T_{amb} = 125 °C, I_{OUT} = 1 A	300	mJ
P_{TOT}	Power dissipation at T_c = 25 °C	Internally limited	W
T_J	Junction operating temperature	Internally limited	°C
T_{STG}	Storage temperature	-55 to 150	°C

Thermal data

Table 5. Thermal data

Symbol	Parameter		Value	Unit
$R_{th(JC)}$	Thermal resistance junction to case(1)	Max.	1	°C/W
$R_{th(JA)}$	Thermal resistance junction to ambient(2)	Max.	See *Figure 11 on page 15*	°C/W

1. Per channel.
2. When mounted using minimum recommended pad size on FR-4 board.

4 Electrical characteristics

9 V < V_{CC} < 36 V; -40 °C < T_J < 125 °C; unless otherwise specified.

Table 6. Power section

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{CC}	Supply voltage		9	-	45	V
$R_{DS(ON)}$	On-state resistance	I_{OUT} = 0.5 A at T_J = 25 °C I_{OUT} = 0.5 A	-	0.080	 0.150	Ω Ω
V_{CLAMP}	Clamp voltage	Is = 20 mA	45	-	52	V
I_S	Supply current	All channel in off-state On-state with V_{IN} =5 V (T_J = 125 °C)	-	300 1.9	 4	µA mA
I_{LGND}	Output current at turn-off	V_{CC} = V_{DIAG} = V_{IN} = V_{GND} = 24 V, V_{OUT} = 0 V	-	-	1	mA
$V_{OUT(OFF)}$	Off-state output voltage	V_{IN} = 0 V and I_{OUT} = 0 A	-	-	3	V
$I_{OUT(OFF)}$	OFF-state output current	V_{IN} = V_{OUT} = 0 V	0	-	5	µA
$I_{OUT(OFF1)}$		V_{IN} = 0 V; V_{OUT} = 4 V	-35	-	0	µA

Table 7. Timing (V_{CC} = 24 V, R_{LOAD} = 48 Ω)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(ON)}$	Turn-on delay time of output current	I_{OUT} = 0.5 A, resistive load Input rise time < 0.1 µs, T_J = 25 °C	-	8	-	µs
t_r	Rise time of output current	I_{OUT} = 0.5 A, resistive load Input rise time < 0.1 µs, T_J = 25 °C	-	15	-	µs
$t_{d(ON)}$ + t_r	Turn-on response	I_{OUT} = 0.5 A, resistive load Input rise time < 0.1 µs, T_J = 25 °C	-	-	35	µs
$t_{d(OFF)}$	Turn-off delay time of output current	I_{OUT} = 0.5 A, resistive load Input rise time < 0.1 µs, T_J = 25 °C	-	10	-	µs
t_f	Fall time of output current	I_{OUT} = 0.5 A, resistive load Input rise time < 0.1 µs, T_J = 25 °C	-	7	-	µs
$t_{d(OFF)}$ + t_f	Turn-off response	I_{OUT} = 0.5 A, resistive load Input rise time < 0.1 µs, T_J = 25 °C	-	-	40	µs
t_{DOL}	Delay time for open-load detection	-	-	500	-	µs
$dV/dt_{(ON)}$	Turn ON voltage slope	-	-	3	-	V/µS
dV/dt(off)	Turn OFF voltage slope	-	-	4	-	V/µS

Table 8. Logical input

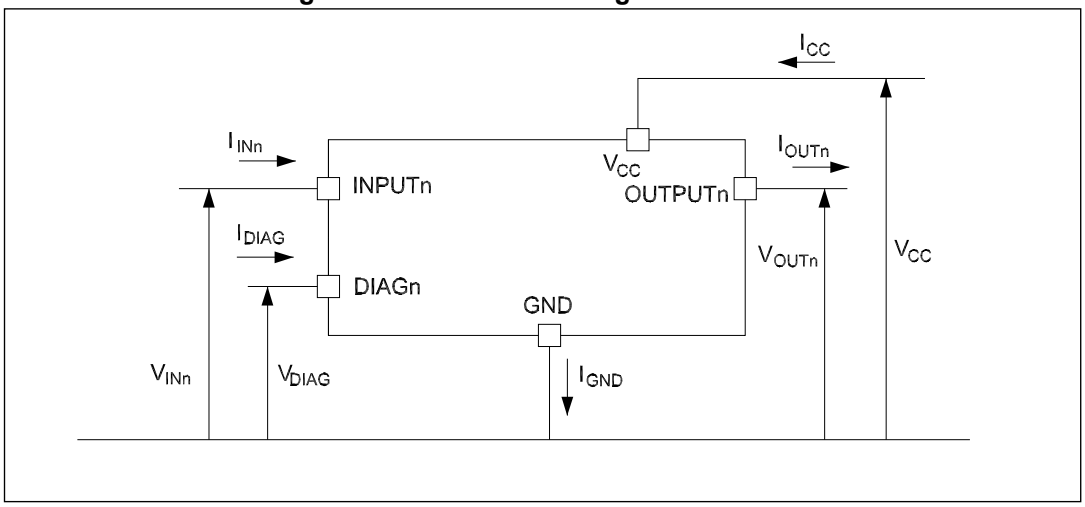
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{IL}	Input low level voltage	-	-	-	0.8	V
V_{IH}	Input high level voltage	-	2.20	-	-	V
$V_{I(HYST)}$	Input hysteresis voltage	-	-	0.15	-	V
I_{IN}	Input current	V_{IN} = 15 V	-	-	10	µA
		V_{IN} = 36 V	-	-	210	

Table 9. Protection and diagnostic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{DIAG} (1)	Diag voltage output low	I_{DIAG} = 1.5 mA (fault condition)	-	-	0.6	V
V_{USD}	Undervoltage protection	-	7	-	9	V
V_{USDHYS}	Undervoltage hysteresis	-	0.4	0.5	-	V
I_{LIM}	DC short-circuit current	V_{CC} = 24 V; R_{LOAD} < 10 mΩ	1	-	2	A
I_{LDIAG}	Diag leakage current	V_{CC} = 32 V	-	30	-	µA
V_{OL}	Open-load off-state voltage detection threshold	V_{IN} = 0 V	2	3	4	V
T_{TSD}	Junction shutdown temperature	-	150	170	-	°C
T_R	Junction reset temperature	-	135	155	200	°C
T_{HIST}	Junction thermal hysteresis	-	7	15	-	°C
T_{CSD}	Case shutdown temperature	-	125	130	135	°C
T_{CR}	Case reset temperature	-	110	-	-	°C
T_{CHYST}	Case thermal hysteresis	-	7	15	-	°C
V_{demag}	Output voltage at turn-OFF	I_{OUT} = 0.5 A; L_{LOAD} >= 1 mH	V_{CC}-45	V_{CC}-50	V_{CC}-52	V

1. Diag determination > 100 ms after the switching edge.

Figure 3. Current and voltage conventions



5 Truth table

Table 10. Truth table

IC condition	INPUTn	OUTPUTn	DIAGn
Normal operation	L H	L H	H H
Overtemperature	L H	L L	H L
Undervoltage	L H	L L	X X
Shorted-load (current limitation)	L H	L X	H H
Output voltage > V_{OL}	L H	Z(1) H	L H
Short to V_{CC}	L H	H H	L H

1. Z = depending on the external circuit.

6 Switching waveforms

Figure 4. Switching waveforms

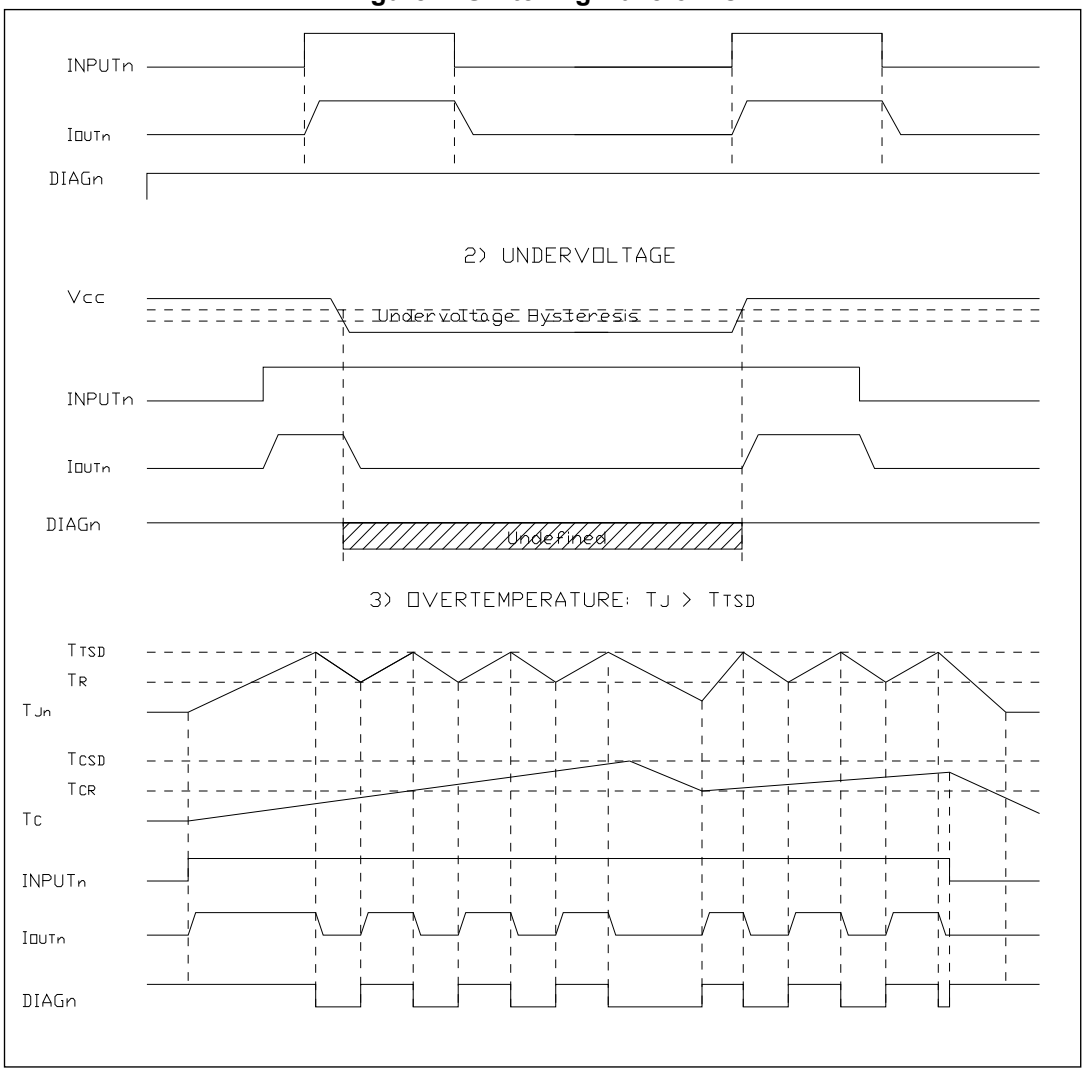


Figure 5. Switching waveforms (continued)

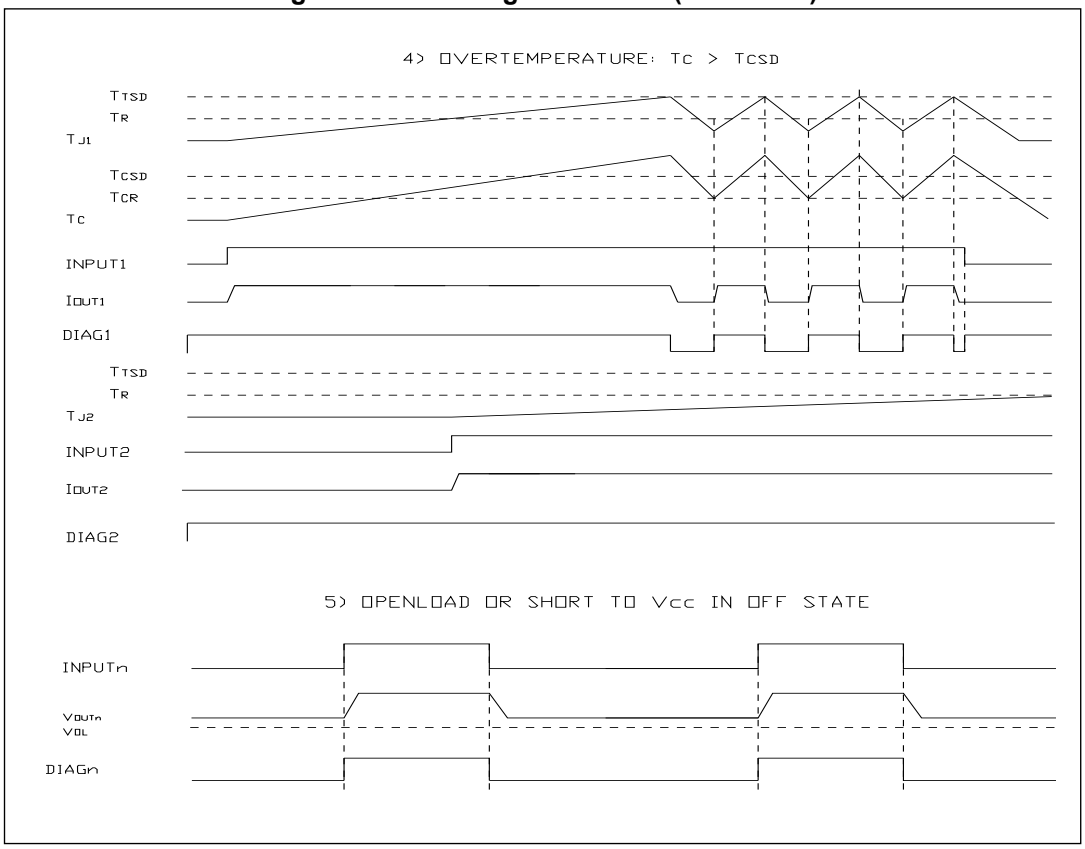


Figure 6. Switching parameter test conditions

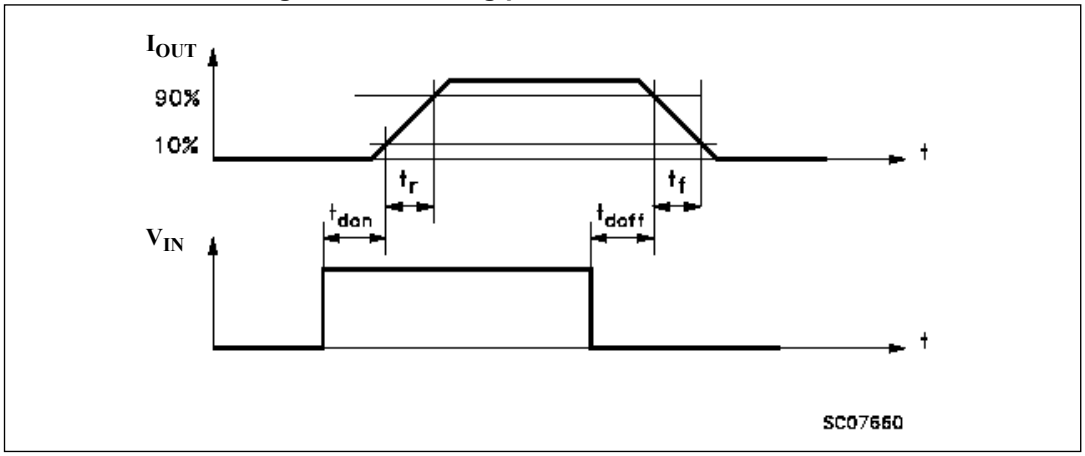
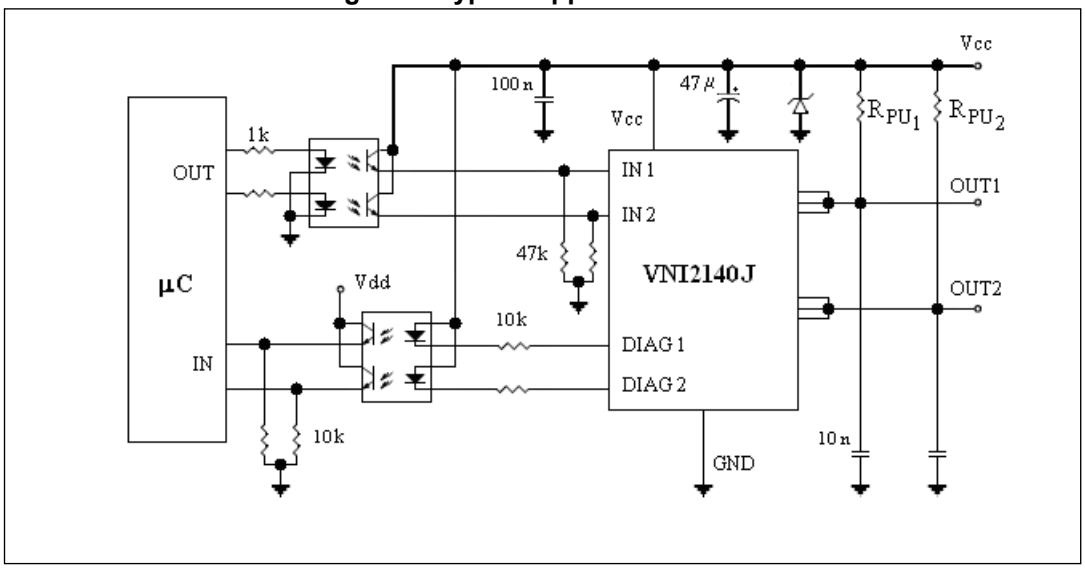


Figure 7. Typical application circuit



7 Open-load

In order to detect the open-load fault a pull-up resistor must be connected between the V_{CC} line and the output pin.

In a normal condition a current flows through the network made up of a pull-up resistor and a load. The voltage across the load is less than V_{OLMIN}; so the diag pin is kept high.

This is the result in the condition:

Equation 1

$$V_{CC}\frac{R_{LOAD}}{R_{LOAD}+R_{PU}} < V_{OLMIN}$$

or

Equation 2

$$\left(\frac{V_{CC}}{V_{OLMIN}} - 1\right) \cdot R_{LOAD} < R_{PU}$$

When a open-load event occurs the voltage on the output pin rises to a value higher than V_{OLMAX} (depending on the pull-up resistor). The diag pin will go down.

This result in the condition:

Equation 3

$$R_{PU} < \frac{V_{CC} - V_{OLMAX}}{|I_{OUT(OFF1)MIN}|}$$

Figure 8. Open-load detection

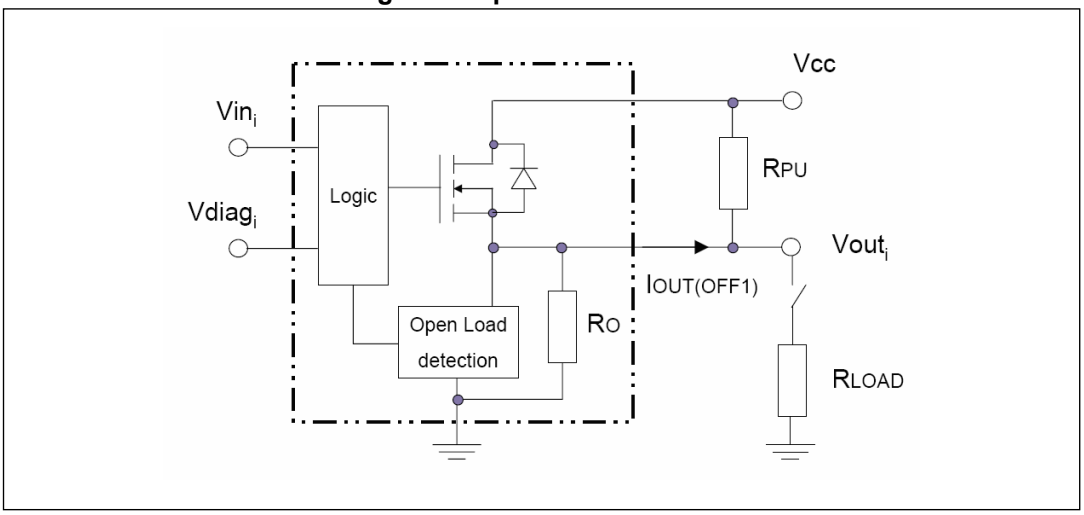
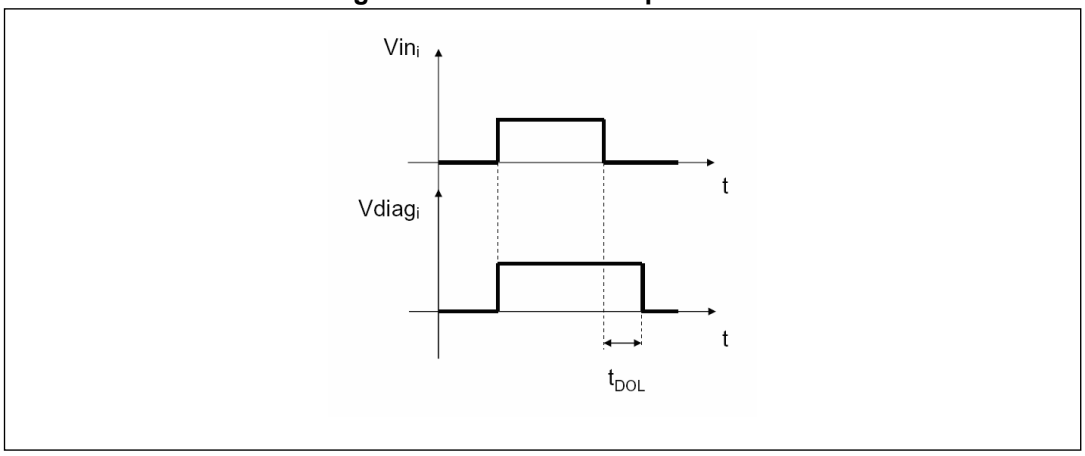
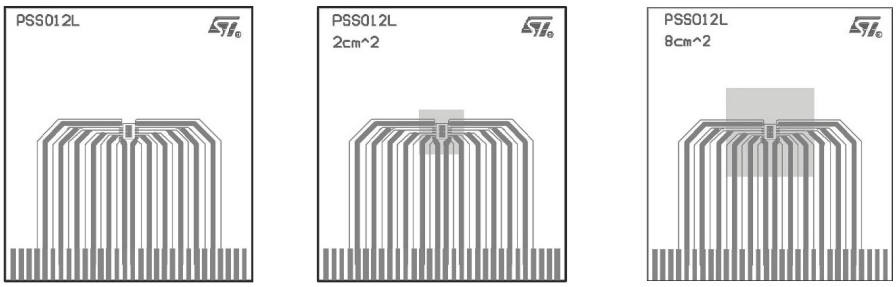


Figure 9. Turn-on/off to open-load



8 Package and PCB thermal data

Figure 10. PowerSSO-12 PC board



Layout condition of R_{th} and Z_{th} measurements (PCB: Double layer, Thermal Vias, FR4 area= 77mm x 86mm, PCB thickness=1.6mm, Cu thickness=70µm (front and back side), Copper areas: from minimum pad lay-out to 8cm^2).

Figure 11. R_{thJA} vs PCB copper area in open box free air condition

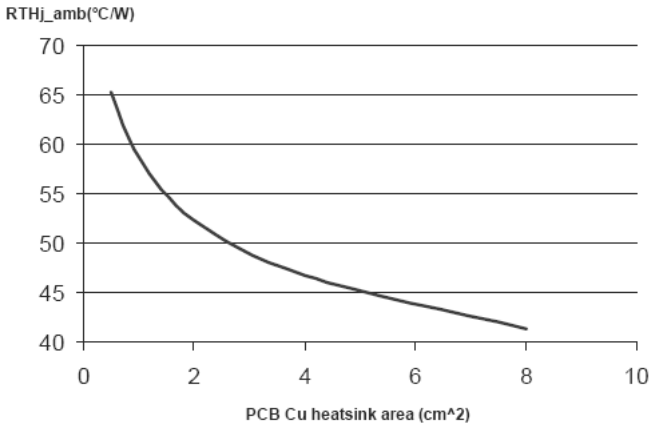
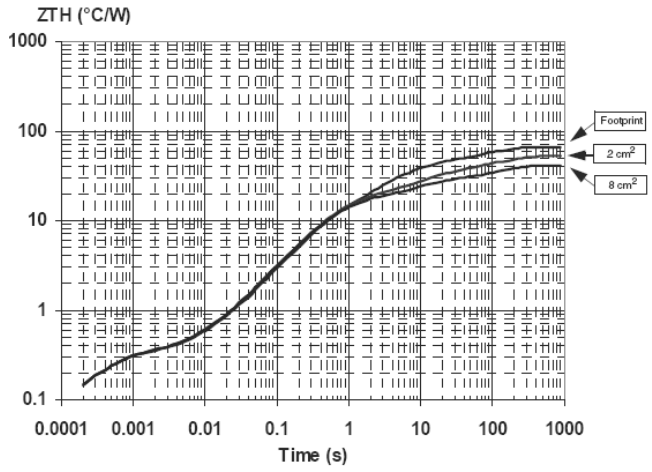


Figure 12. PowerSSO-12 thermal Impedance junction ambient single pulse



Pulse calculation formula

Equation 4

$$Z_{TH\delta} = R_{TH} \times \delta + Z_{THtp} (1 - \delta)$$

where $\delta = t_P/T$

Figure 13. Thermal fitting model of a double channel HSD in PowerSSO-12

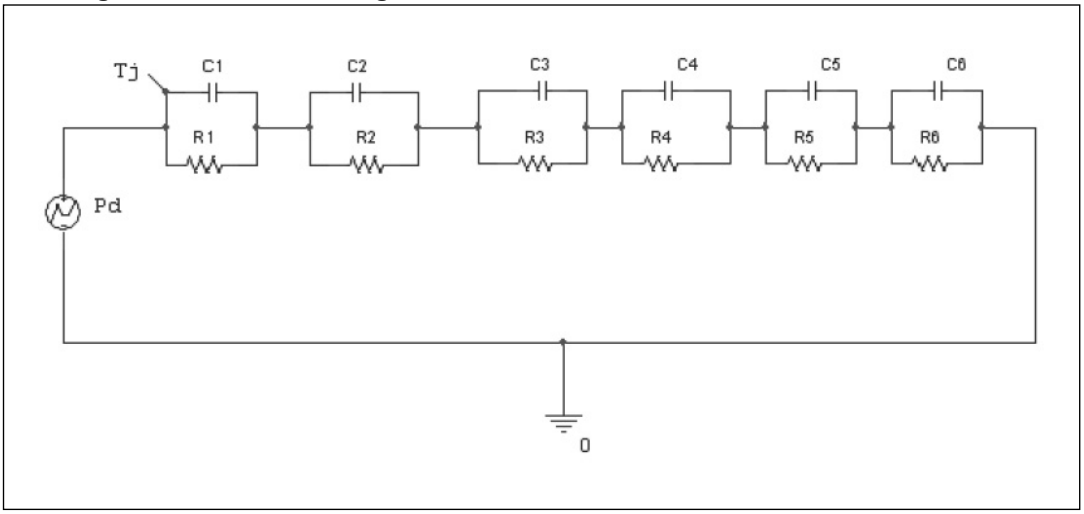


Table 11. Thermal parameter

Area/island (cm^2)	Footprint	2	8
R1 (°C/W)	0.1	-	-
R2 (°C/W)	0.2	-	-
R3 (°C/W)	7	-	-
R4 (°C/W)	10	10	9
R5 (°C/W)	22	15	10
R6 (°C/W)	26	20	15
C1 (W.s/°C)	0.0001	-	-
C2 (W.s/°C)	0.002	-	-
C3 (W.s/°C)	0.05	-	-
C4 (W.s/°C)	0.2	0.1	0.1
C5 (W.s/°C)	0.27	0.8	1
C6 (W.s/°C)	3	6	9

9 Reverse polarity protection

Reverse polarity protection can be implemented on board using two different solutions:

1. Placing a resistor (RGND) between IC GND pin and load GND.
2. Placing a diode between IC GND pin and load GND.

If option 1 is selected, the minimum resistance value has to be selected according to the following equation:

Equation 5

$$R_{GND} \geq V_{CC}/I_{GNDcc}$$

where IGNDcc is the DC reverse ground pin current and can be found in *Section 3: Maximum ratings* of this datasheet.

Power dissipated by R_{GND} during reverse polarity situations is:

Equation 6

$$P_D = (V_{CC})^2/R_{GND}$$

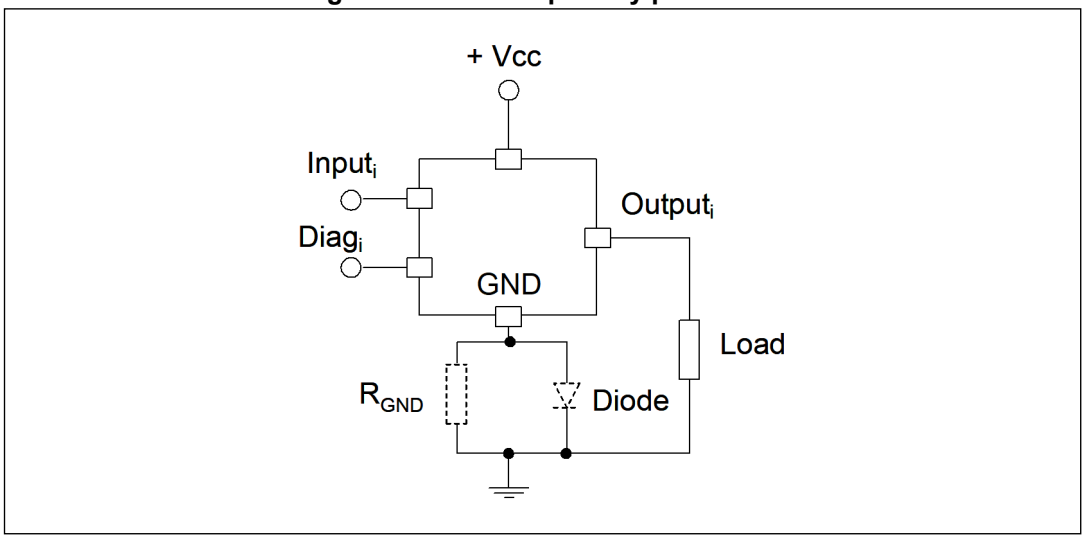
If option 2 is selected, the diode has to be chosen by taking into account V_{RRM} >|Vcc| and its power dissipation capability:

Equation 7

$$P_D \geq I_S * V_F$$

*Note: In normal operation (no reverse polarity), there is a voltage drop (ΔV) between GND of the device and GND of the system. Using option 1, ΔV = Rgnd * Icc. Using option 2, ΔV = VF@(IF).*

Figure 14. Reverse polarity protection



10 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

10.1 PowerSSO-12™ package information

Figure 15. PowerSSO-12™ package outline

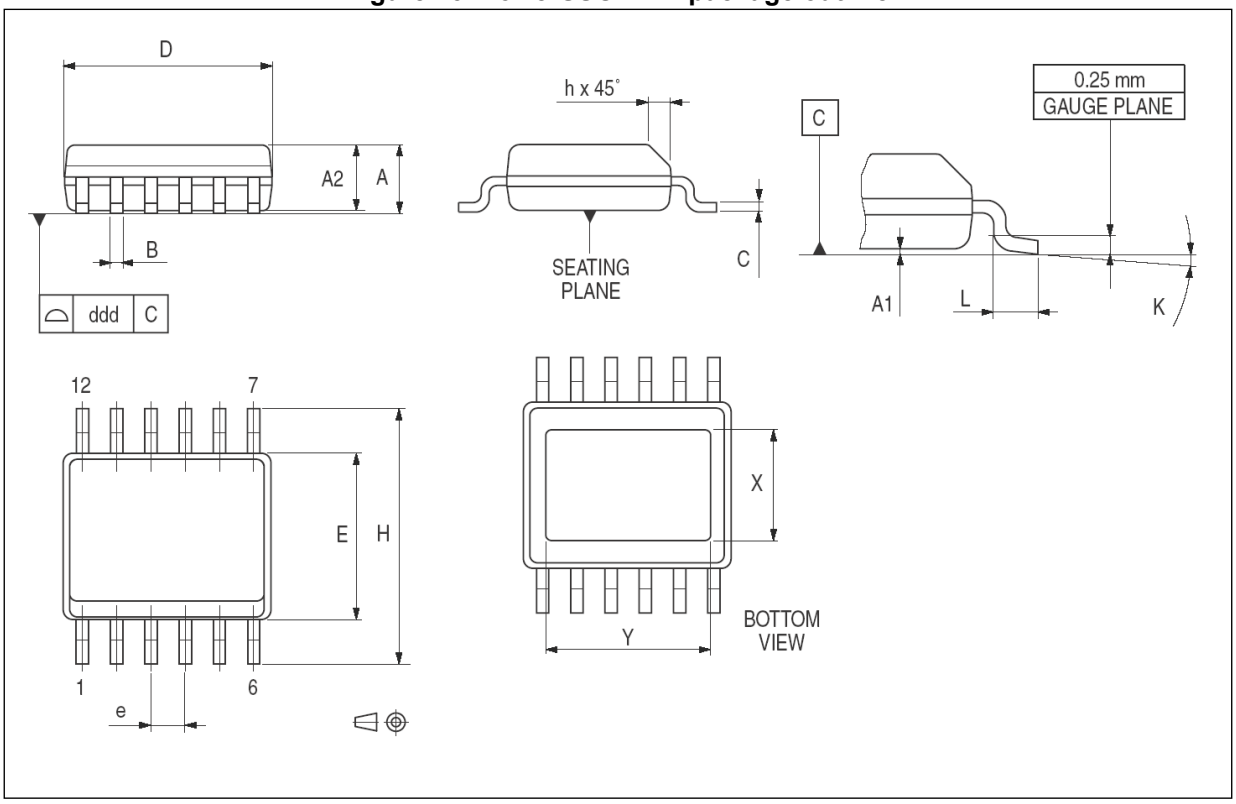
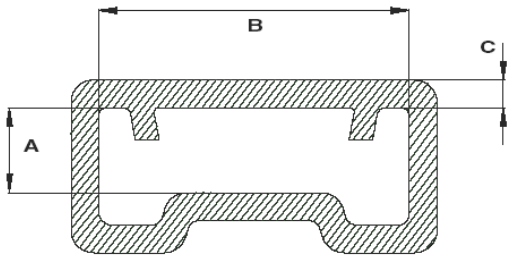


Table 12. PowerSSO-12™ mechanical data

Symbol	Dimensions (mm)		
	Min.	Typ.	Max.
A	1.250	-	1.620
A1	0.000	-	0.100
A2	1.100	-	1.650
B	0.230	-	0.410
C	0.190	-	0.250
D	4.800	-	5.000
E	3.800	-	4.000
e	-	0.800	-
H	5.800	-	6.200
h	0.250	-	0.500
L	0.400	-	1.270
k	0°	-	8°
X	1.900	-	2.500
Y	3.600	-	4.200
ddd	-	-	0.100

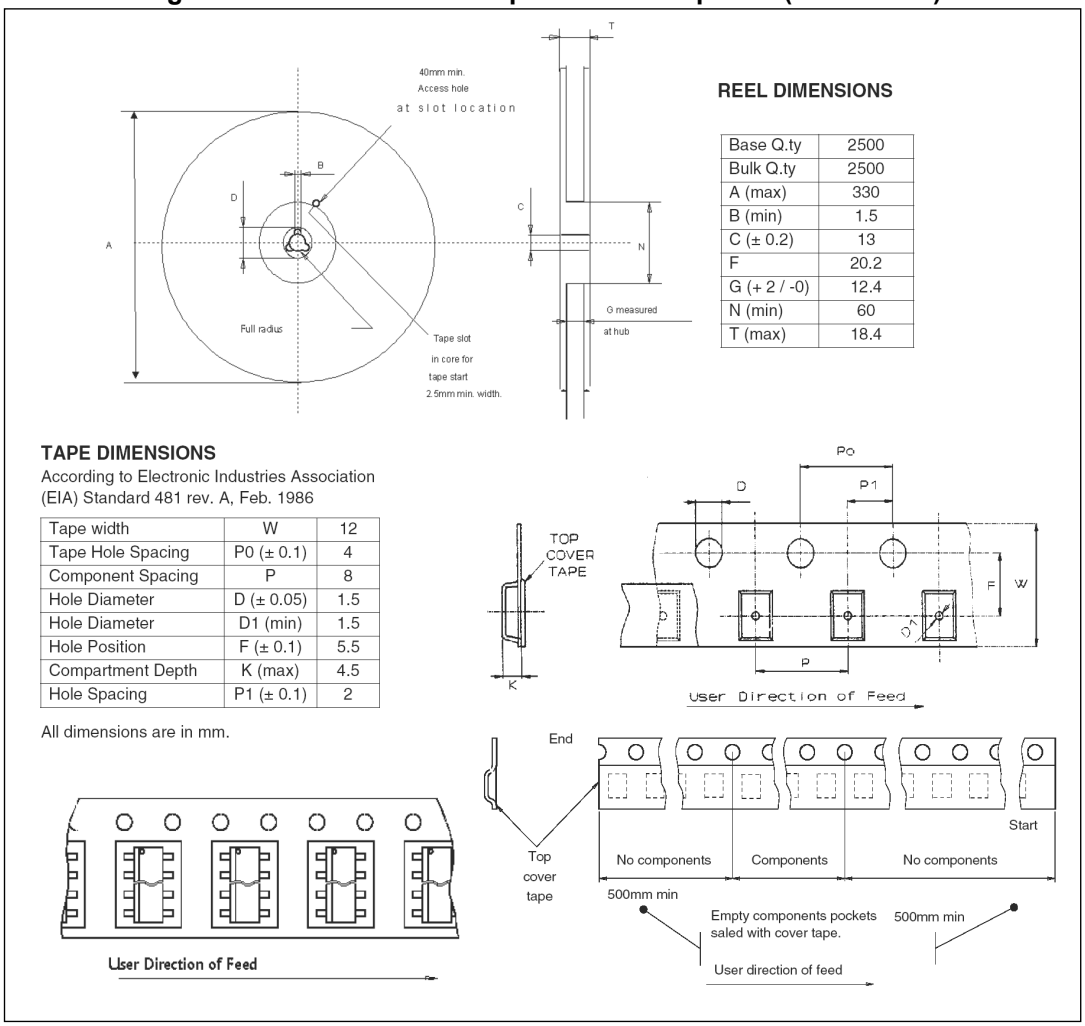
Figure 16. PowerSSO-12™ tube shipment (no suffix)



Base Q.ty	100
Bulk Q.ty	2000
Tube length (± 0.5)	532
A	1.85
B	6.75
C (± 0.1)	0.6

All dimensions are in mm.

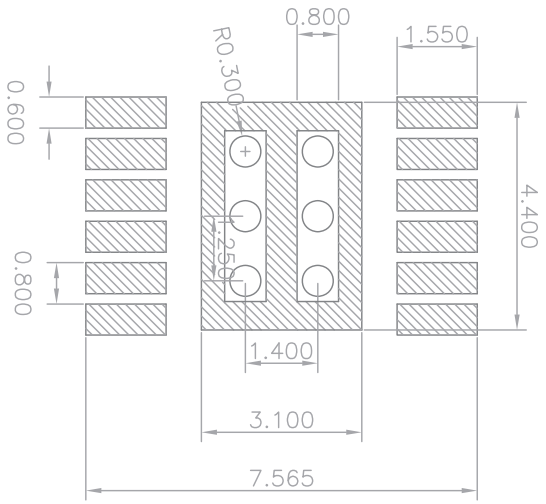
Figure 17. PowerSSO-12™ tape and reel shipment (suffix “TR”)



Base Q.ty	2500
Bulk Q.ty	2500
A (max)	330
B (min)	1.5
C (± 0.2)	13
F	20.2
G (+ 2 / -0)	12.4
N (min)	60
T (max)	18.4

Tape width	W	12
Tape Hole Spacing	P0 (± 0.1)	4
Component Spacing	P	8
Hole Diameter	D (± 0.05)	1.5
Hole Diameter	D1 (min)	1.5
Hole Position	F (± 0.1)	5.5
Compartment Depth	K (max)	4.5
Hole Spacing	P1 (± 0.1)	2

Figure 18. Suggested footprint



11 Revision history

Table 13. Document revision history

Date	Revision	Changes
16-Dec-2008	1	Initial release
29-Apr-2009	2	Updated *Table 5 on page 6*
03-Jul-2009	3	Updated features in coverpage and *Table 5 on page 6*
27-Aug-2009	4	Updated *Section 9: Reverse polarity protection*
25-Mar-2010	5	Updated Coverpage and *Table 4 on page 5*
26-Apr-2010	6	Updated *Table 5 on page 6*
21-Jul-2010	7	Updated *Table 8 on page 7*
15-Nov-2011	8	Updated *Figure 18 on page 21*
09-Nov-2017	9	Updated *Table 4 on page 5* and *Table 7 on page 6*. Minor modifications throughout document.
10-Dec-2019	10	Updated *Section 9: Reverse polarity protection*

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